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Journal Information

Journal Title	SOLDERING & SURFACE MOUNT TECHNOLOGY
Publisher	EMERALD GROUP PUBLISHING LTD
ISSN	0954-0911
E-ISSN	1758-6836
Database	Clarivate
Domain	Health Sciences, Physical Sciences, Social Sciences

Classification History

Year	A+	A	B	C
2026		✓	✓	
2025		✓	✓	
2024		✓	✓	
2023		✓	✓	
2021/2022		✓	✓	
2020		✓	✓	
2019		✓	✓	
2018		✓		

Classification: The table above shows all journal classifications recorded for each classification year in the Green Journals database. A journal may have more than one classification in the same year.

Recent Articles

Optimized microstructure and enhanced multifunctional properties of Sn-25Bi solder alloys reinforced with exfoliated Ti3C2Tx MXene nanosheets
2026-10-15 Vol. 38 Issue 5 Pages 355-365
Authors: Sallah A. Al Hashedi, Hamed Al-Sorory, Adil Alshoaibi et al.
DOI: 10.1108/ssmt-05-2026-0044

Thermal effects of die-attach void fraction and position in high-power LED packages: a three-dimensional finite-element study
2026-10-12 Vol. 38 Issue 5 Pages 409-417
Authors: Viet-Dung Le
DOI: 10.1108/ssmt-07-2026-0062

Experimental and numerical investigation of Sn–BiSAC hybrid solder joints with process optimization via Taguchi method
2026-9-24 Vol. 38 Issue 5 Pages 379-398
Authors: Atikah Liyana Ahamad, Muhamed Abdul Fatah Muhamed Mukhtar, Muhammad Khairul Anuar Mohamed et al.
DOI: 10.1108/ssmt-05-2026-0035

Interfacial IMC evolution and mechanical performance of In-doped Sn58Bi solder joints subjected to isothermal aging
2026-9-10 Vol. 38 Issue 5 Pages 399-408
Authors: Lei Sun, Wenhao Wang, Jiaxin Yu et al.
DOI: 10.1108/ssmt-07-2026-0060

Influence of loading time on the microstructures and performance of Cu/Al joints by bonding at a low temperature of 160°C
2026-8-28 Vol. 38 Issue 5 Pages 366-378
Authors: Guisheng Gan, JunFeng Dou, JiaJun Zhang et al.
DOI: 10.1108/ssmt-05-2026-0033

Reliability analysis of large area sintered Cu interconnects based on simulation and thermal shock test
2026-8-11 Pages 1-11
Authors: Jiaqi Gao, Yang Liu, Yue Gao et al.
DOI: 10.1108/ssmt-11-2025-0071

Research on the protrusion behavior and evolution mechanism of TSV in 3D packaging under high temperature
2026-8-3 Pages 1-9
Authors: Jiahao Liu, Lijin Qiu, Bin Zhou et al.
DOI: 10.1108/ssmt-02-2026-0014

Retraction notice: Reliability modeling and assessment of solder joints of electronic assemblies under mixed exposure to mechanical loads
2026-7-28 Vol. 38 Issue 5 Pages 418-418
DOI: 10.1108/ssmt-07-2026-0055

Influence of electron irradiation on the power cycling lifetime of SiC MOSFETs
2026-6-15 Vol. 38 Issue 5 Pages 343-354
Authors: Yuxiong Xue, Jiayan Li, Bo Mei et al.
DOI: 10.1108/ssmt-03-2026-0027

Mechanical response of BGA micro solder joints with different shape combinations under thermal cycling
2026-6-10 Vol. 38 Issue 5 Pages 321-330
Authors: Xiangxia Kong, Zuchen Liu, Lu Yang et al.
DOI: 10.1108/ssmt-01-2026-0003